Camera Module

MB1066

Table of contents

Sheet 1: Project overview (this page)

Sheet 2: MB1066

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.

Notes to generate the board layout.

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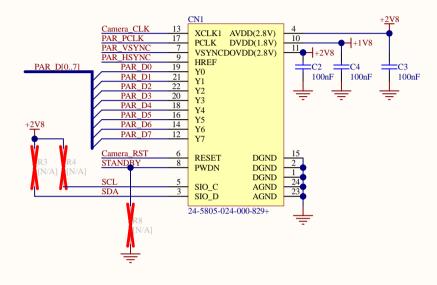
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| | Title: Project_Overview | | | |
|--|---|------------------|-------------------|---|
| | Project: Camera Module Variant: Default | | | |
| | | | | / |
| | Revision: A-02 | | Reference: MB1066 | |
| | Size: A4 | Date: 03/06/2013 | Sheet: 1 of 2 | |





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